

AMENDMENTS TO THE SPECIFICATION

On page 4, please amend the last paragraph beginning with “According to a preferred embodiment of the invention, shielding with respect...” as follows:

According to a preferred embodiment of the invention, shielding with respect to most of the volume of air, which is enclosed in the second cavity is achieved by the fact that a bonding layer, which is provided in the chip card of the generic type for securing the carrier substrate to the chip card body, is also provided in the second cavity. The bonding layer is usually only arranged in the region of the base surface of the first cavity, outside the second cavity, and in the region of the second cavity has a cut-out, since the electrical contacts to the semiconductor chip are arranged there, at the level of the base surface of the first cavity. According to a preferred embodiment of the invention, there is provision for the bonding layer to extend from the base of the first cavity into the interior of the second cavity and to cover a region of the semiconductor chip. The same bonding layer which, in order to secure the carrier substrate, is customarily provided only at the base surface outside the second cavity, therefore, according to a preferred embodiment of the invention, at the same time within the second cavity covers the semiconductor chip on its underside and extends next to the side faces of the semiconductor chip all the way to the base surface of the first cavity, with the result that the air volume of the second cavity is divided in two. The bonding layer shields most of the air volume from the semiconductor chip, so that only a fraction of the moisture and/or pollutants which are present comes into contact with the semiconductor chip. This results in substantial shielding of the microclimate which is achieved without additional cost outlay. In particular, there is provision for the bonding layer to surround the semiconductor chip in the second cavity from below. Since the bonding layer encloses the semiconductor chip projecting above the underside of

the carrier substrate, it represents an additional protective covering and therefore, this bonding layer is also referred to herein as a “protective covering layer.”